

TEMIC

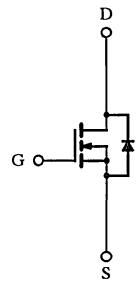
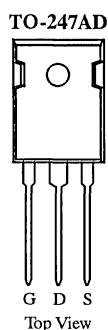
Siliconix

SMW45N10

N-Channel Enhancement-Mode Transistor

Product Summary

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
100	0.040	45



Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	45	A
		27	
Pulsed Drain Current	I_{DM}	180	A
Avalanche Current	I_{AR}	45	
Avalanche Energy	E_A	300	mJ
Repetitive Avalanche Energy ^a	E_{AR}	20	
Power Dissipation	P_D	150	W
		60	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	°C
Lead Temperature (1/16" from case for 10 sec.)	T_L	300	

6**N-/P-Channel
MOSFETs**

Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient	R_{thJA}		40	°C/W
Junction-to-Case	R_{thJC}		0.83	
Case-to-Sink	R_{thCS}	0.35		

Notes:

a. Duty cycle $\leq 1\%$

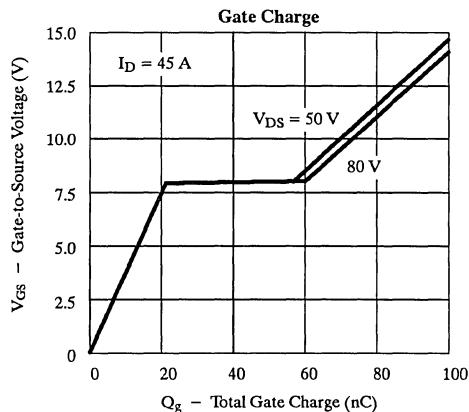
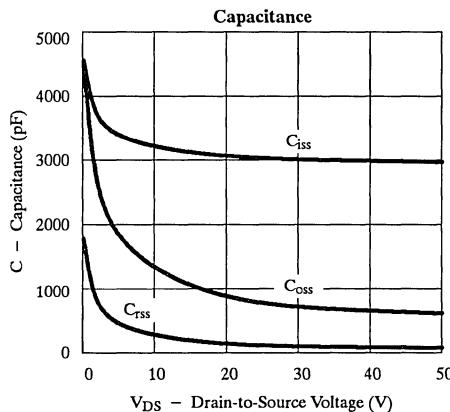
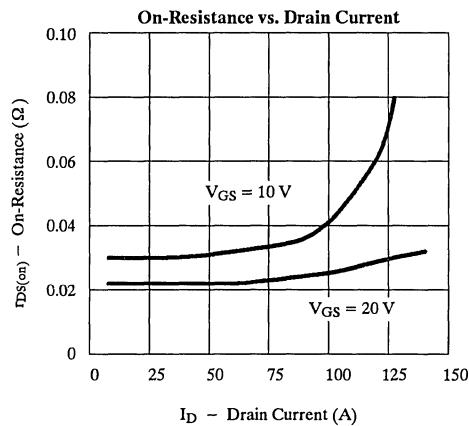
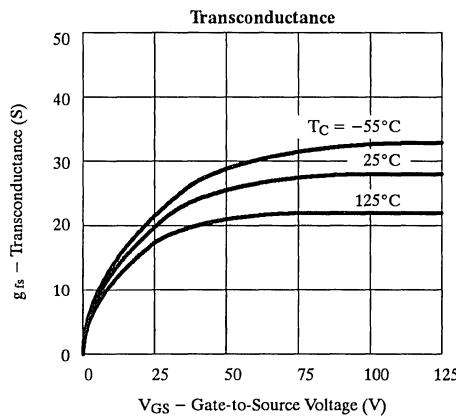
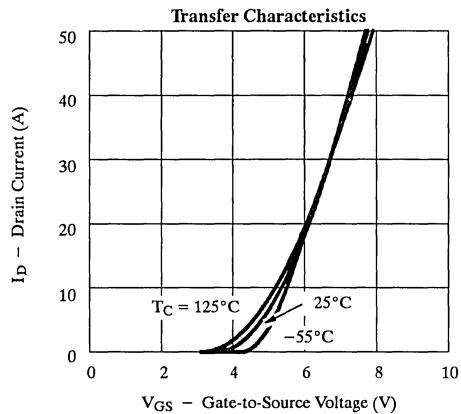
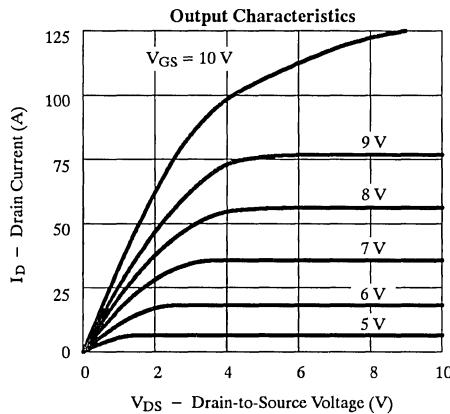
Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

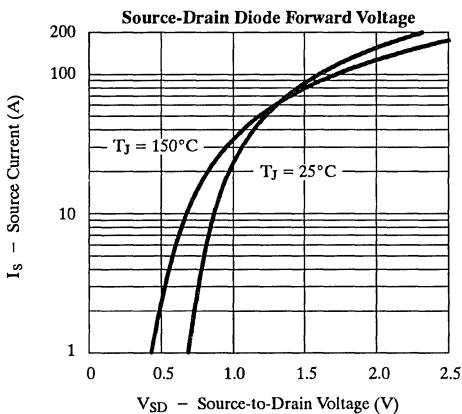
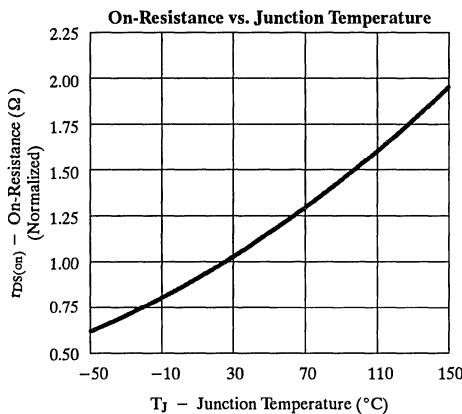
Parameter	Symbol	Test Condition	Min	Typ ^a	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2.0		4.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$		25		μA
		$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^\circ\text{C}$		250		
On-State Drain Current ^b	$I_{D(\text{on})}$	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	45			A
Drain-Source On-State Resistance ^b	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 27 \text{ A}$		0.030	0.040	Ω
		$V_{GS} = 10 \text{ V}, I_D = 27 \text{ A}, T_J = 125^\circ\text{C}$		0.058	0.072	
Forward Transconductance ^b	g_{fs}	$V_{DS} = 10 \text{ V}, I_D = 27 \text{ A}$	15			S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		3000		pF
Output Capacitance	C_{oss}			750		
Reverse Transfer Capacitance	C_{rss}			150		
Total Gate Charge ^c	Q_g	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 45 \text{ A}$		72	100	nC
Gate-Source Charge ^c	Q_{gs}			26	35	
Gate-Drain Charge ^c	Q_{gd}			31	40	
Turn-On Delay Time ^c	$t_{d(on)}$	$V_{DD} = 50 \text{ V}, R_L = 1.1 \Omega$ $I_D \approx 45 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.5 \Omega$		17	30	ns
Rise Time ^c	t_r			80	120	
Turn-Off Delay Time ^c	$t_{d(off)}$			40	60	
Fall Time ^c	t_f			20	40	
Source-Drain Diode Ratings and Characteristics ($T_C = 25^\circ\text{C}$)						
Continuous Current	i_S				45	A
Pulsed Current	I_{SM}				180	
Forward Voltage ^b	V_{SD}	$I_F = 45 \text{ A}, V_{GS} = 0 \text{ V}$			2.5	V
Reverse Recovery Time	t_{rr}	$I_F = 45 \text{ A}, dI_F/dt = 100 \text{ A}/\mu\text{s}$		130		ns
Reverse Recovery Charge	Q_{rr}			0.31		μC

Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- c. Independent of operating temperature.

Typical Characteristics (25°C Unless Otherwise Noted)



SMW45N10**Typical Characteristics (25°C Unless Otherwise Noted)****Thermal Ratings**